

HANDLING PROCEDURES AND REMARKS FOR
 CONNECTOR USED FOR FPC/FFC WITH 1mm CONTACT
 SPACING COPING WITH AUTOMATIC MOUNTING AND SMT
 HFW__R-1/2STE_

1. Mounting method of the connector on P.C.Board

This connector applies the construction which copes with automatic mounting and SMT. Therefore please proceed reflow soldering after mounting it on P.C.Board by automatic mounting machine.

Packing style of connector	Plastic tape which cope with JIS C 0806
Automatic mounting machine	One by one system
Soldering	Reflow soldering (V.P.S.Infrared reflow system etc.)

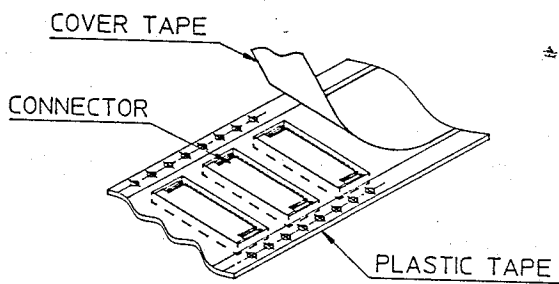
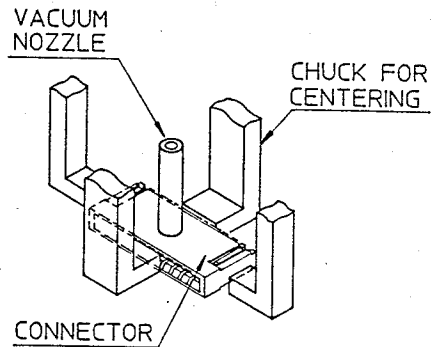
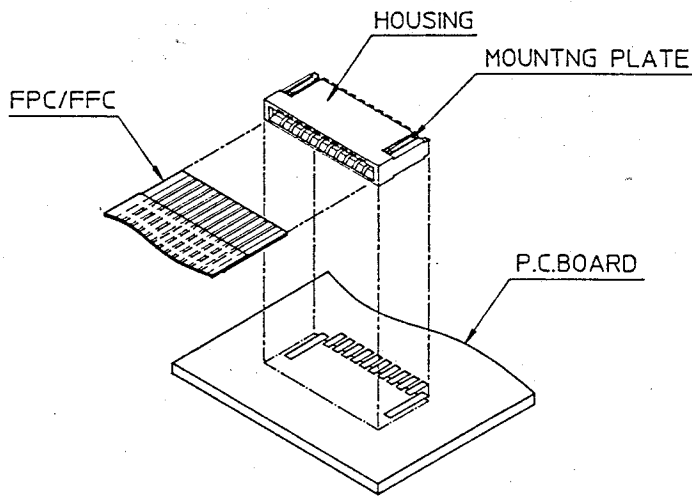


FIGURE FOR
PLASTIC TAPE PACKING



AUTOMAATIC MOUNTING MACHINE :
CHUCK MECHANISM

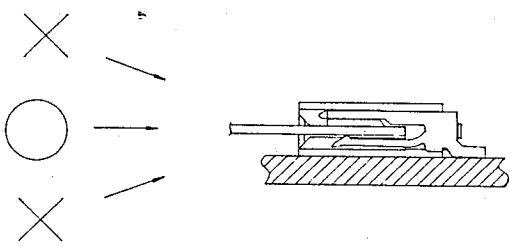
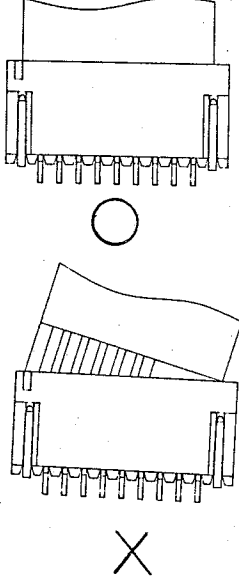


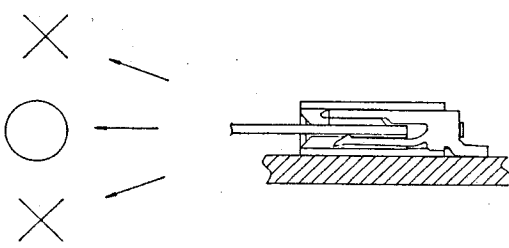
CONNECTOR MOUNTING FIGURE

Note) Please refer to the drawings attached to the specification for details of dimensions etc.

2. Handling procedure details and remarks

No.	Procedure	Remarks
2-1	<p><u>Cream solder coating</u> Coat cream solder with adequate quantity on P.C.B. pattern. <Recommended cream solder> JIS Z 3282 H60A or H63A (Use solder contained with 2.5~3.0 wt% silver if necessary.) Solder particle : More than 325 mesh Flux : Inactive Rosin family flux</p>	<ul style="list-style-type: none"> • Please refer to the drawings attached to the specification for recommended P.C.B pattern dimensions. • Please coat cream solder with adequate quantity by adjusting thickness of stencil.
2-2	<p><u>Mounting on P.C.Board</u> By using automatic mounting machine (One by one system) which copes with plastic tape packing. Mount the connector on predetermined position on P.C.Board coated with cream solder.</p>	<ul style="list-style-type: none"> • Please confirm carefully mounting accuracy of automatic mounting machine and dimensional accuracy of P.C.B. • Use by selecting adequate one for vacuum nozzle diameter of automatic mounting machine.

No.	Procedure	Remarks
2-3	<p><u>Reflow soldering</u></p> <p>1) Soldering method Solder by using reflow bath. <Recommended soldering condition> V.P.S.</p> <p>a) Preheat 150°C 60~120 sec. b) Soldering 215°C 10~30 sec.</p> <p>Infrared ray reflow or hot air reflow</p> <p>a) Preheat 150°C 120sec. b) Soldering peak 240°C 215°C 10~30sec.</p> <p><u>Note</u> Temperature shown above Indicates it of contact terminal portion.</p> <p>2) Cleaning Cleaning of flux residue is recommended by considering the reliability of insulation resistance and corrosion characteristics after soldered.</p>	<p>Set temperature on the surface of P.C.B. under 260°C.</p> <p>• There is one which has an influence on the characteristic of the connector in cleaning liquid. • Please confirm the kind of cleaning liquid or consult us separately.</p>
2-4	<p><u>Connection of conductor(FPC/FFC)</u></p> <p>1) Match conductive side of conductor (Finger portion) to connecting side of connector.</p> <p>2) Insert conductor straight horizontally into P.C.Board from connector insertion window until it hits inner bottom of housing.</p> 	<p>At the condition of being connector inserted the conductor must be vertical to the connector by all means.</p> 

2-5	<p><u>Extracting conductor(FPC/FFC)</u> Extracting conductor straight horizontally for P.C.Board.</p> 	Please pay special attention in case of removing the conductor to slant direction.
-----	---	--

3. Other remarks

- 1) Do not insert lead other than FFC, FPC and probe etc. directly into contacting portion.
Since CIC (Conductor such as silver paste, carbon etc.) can not be used for this product, please consult us separately.
- 2) Do not make any soldering in the condition of being conductor mated.
- 3) Operating force of slider may become larger considerably if number of conductors increase.

4. Storage of connector

- 1) Avoid the places where dust, oil and water etc. are splashed or have direct sunshine.
Solderability may be deteriorated if the connector is stocked for long time under high temperature, high humidity.
- 2) Preferable stock condition
 - Temperature : Less than 30°C
 - Humidity : Less than 60% RH
 - Period : Within 3 months